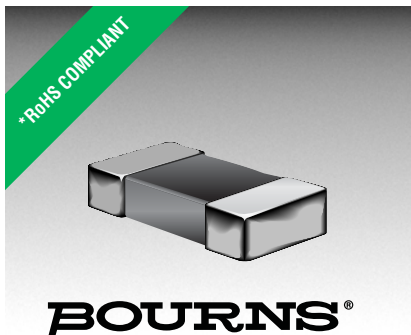




Features

- Monolithic construction offering high reliability
- Magnetically shielded construction providing low radiation
- Low DC resistance
- Low profile
- RoHS compliant*

Applications

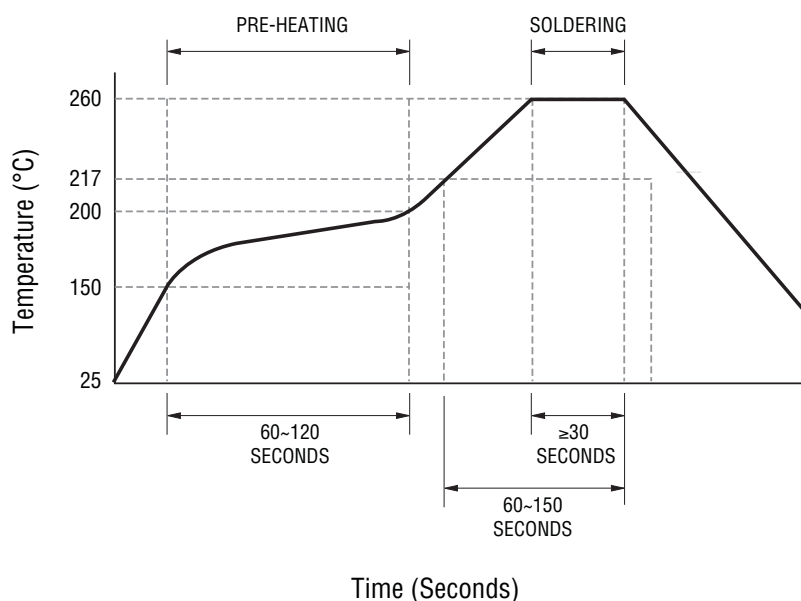
- DC/DC converters for:
 - Smart phones
 - DVCs / DSCs
 - Tablets
 - HDDs / SSDs
 - Mobile electronic devices

CVH252009 Series Multilayer Power Chip Inductors

Electrical Specifications

Bourns® Part No.	Inductance @ 1 MHz		SRF (MHz)	DCR (Ohms)		IDC (mA)
	L (μH)	Tol.		Typ.	Max.	
CVH252009-R47M	0.47	±20 %	100	0.04		1800
CVH252009-1R0M	1.0	±20 %	60	0.055		1600
CVH252009-1R5M	1.5	±20 %	50	0.07		1500
CVH252009-2R2M	2.2	±20 %	40	0.08		1300
CVH252009-3R3M	3.3	±20 %	30	0.10		1200
CVH252009-4R7M	4.7	±20 %	25	0.11		1100

Soldering Profile (Lead Free Solder)



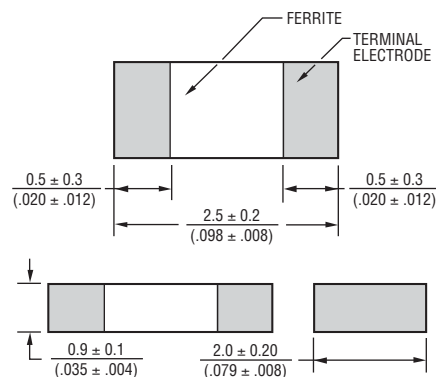
General Specifications

Operating Temperature-55 °C to +125 °C
(Temperature rise included)
Storage Temperature+40 °C max. at 70 % RH
Resistance to Soldering Heat+260 °C
Temperature Rise 40 °C at rated current

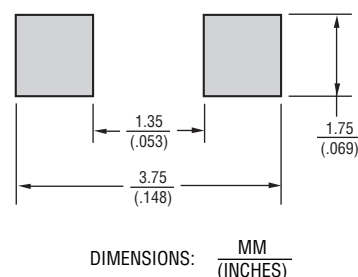
Materials

Core.....Ferrite
Terminal.....Ni/Sn
Packaging..... 3000 pcs. per 7 inch reel

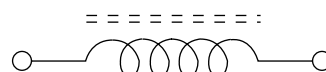
Product Dimensions



Recommended Layout



Schematic



BOURNS®

Asia-Pacific: Tel: +886-2 2562-4117 • Fax: +886-2 2562-4116

Europe: Tel: +41-41 768 5555 • Fax: +41-41 768 5510

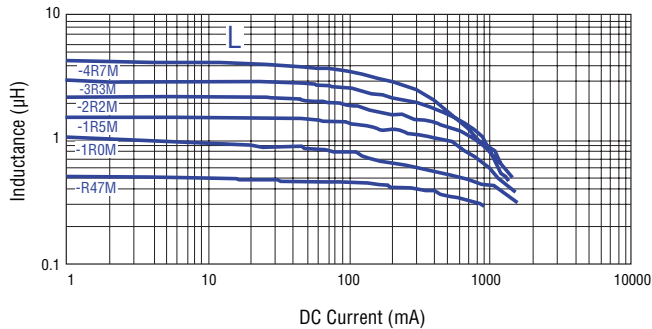
The Americas: Tel: +1-951 781-5500 • Fax: +1-951 781-5700

www.bourns.com

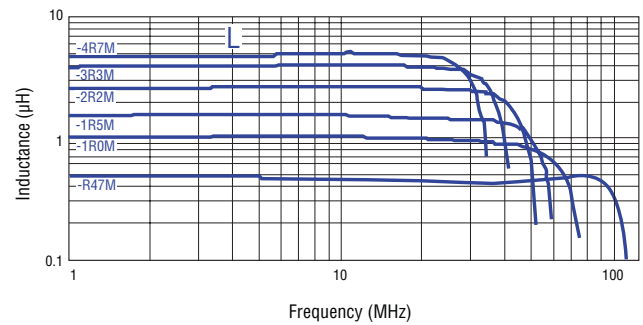
CVH252009 Series Multilayer Power Chip Inductors

BOURNS®

L vs. Idc



L vs. Frequency



Packaging Specifications

